

Features

- Advanced Planar Technology
- Low On-Resistance
- Logic Level Gate Drive
- Dynamic dv/dt Rating
- 150°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified*

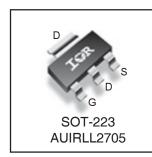
Description

Specifically designed for Automotive applications, this cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low onresistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.





V _{(BR)DSS}	55V	
R _{DS(on)}	max.	0.04Ω
I _D		3.8A



G	D	S
Gate	Drain	Source

Door Dout Number	Doolsons Time	Standard Pa	ack	Orderable Part Number	
Base Part Number	Package Type	Form	Quantity		
AUIRLL2705	SOT-223	Tube	95	AUIRLL2705	
AUINLL2705	301-223	Tape and Reel	2500	AUIRLL2705TR	

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V ®	5.2	
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V ^⑤	3.8	
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ 10V ⑤	3.0	Α
I _{DM}	Pulsed Drain Current ①	30	
P _D @T _A = 25°C	Power Dissipation (PCB Mount) ®	2.1	w
P _D @T _A = 25°C	Power Dissipation (PCB Mount) ^⑤	1.0	T VV
	Linear Derating Factor (PCB Mount) ^⑤	8.3	mW/°C
V_{GS}	Gate-to-Source Voltage	± 16	V
E _{AS}	Single Pulse Avalanche Energy (Thermally Limited) ②	110	mJ
I _{AR}	Avalanche Current ①	3.8	Α
E _{AR}	Repetitive Avalanche Energy ①⑤	0.10	mJ
dv/dt	Peak Diode Recovery dv/dt ③	7.5	V/ns
T_{J}	Operating Junction and	-55 to + 150	°C
T _{STG}	Storage Temperature Range		

Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient (PCB mount, steady state) ^⑤	93	120	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount, steady state) ©	48	60	

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^{*}Qualification standards can be found at http://www.irf.com/



Static Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	55			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.061		V/°C	Reference to 25°C, I _D = 1mA
				0.040		$V_{GS} = 10V, I_D = 3.8A$ ④
R _{DS(on)}	Static Drain-to-Source On-Resistance			0.051	Ω	$V_{GS} = 5.0V, I_D = 3.8A \ \oplus$
				0.065		$V_{GS} = 4.0V, I_D = 1.9A \ \textcircled{4}$
$V_{GS(th)}$	Gate Threshold Voltage	1.0		2.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
gfs	Forward Transconductance	5.1			S	$V_{DS} = 25V, I_D = 1.9A$
I _{DSS}	Drain-to-Source Leakage Current			25	μA	$V_{DS} = 55V, V_{GS} = 0V$
				250		$V_{DS} = 44V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 16V$
	Gate-to-Source Reverse Leakage			-100		V _{GS} = -16V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
Q_g	Total Gate Charge		32	48		$I_D = 3.8A$
Q_{gs}	Gate-to-Source Charge		3.5	5.3	nC	$V_{DS} = 44V$
Q_{gd}	Gate-to-Drain ("Miller") Charge		9.7	14		V _{GS} = 10V, See Fig. 6 and 9 ⊕
t _{d(on)}	Turn-On Delay Time		6.2			$V_{DD} = 28V$
t _r	Rise Time		12		ns	$I_D = 3.8A$
t _{d(off)}	Turn-Off Delay Time		35			$R_G = 6.2\Omega$
t _f	Fall Time	—	22			$R_D = 7.1\Omega$, See Fig. 10 ④
C _{iss}	Input Capacitance		870			$V_{GS} = 0V$
C _{oss}	Output Capacitance		220		pF	$V_{DS} = 25V$
C _{rss}	Reverse Transfer Capacitance		92			f = 1.0MHz, See Fig. 5

Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
Is	Continuous Source Current			0.91		MOSFET symbol p
	(Body Diode)				Α	showing the
I _{SM}	Pulsed Source Current			30		integral reverse G
	(Body Diode) ①					p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C, I_S = 3.8A, V_{GS} = 0V \oplus$
t _{rr}	Reverse Recovery Time		58	88		$T_J = 25^{\circ}C, I_F = 3.8A$
Q _{rr}	Reverse Recovery Charge		140	210	nC	di/dt = 100A/µs ⊕
t _{on}	Forward Turn-On Time	Intrinsio	turn-or	time is	negligible	e (turn-on is dominated by LS+LD)

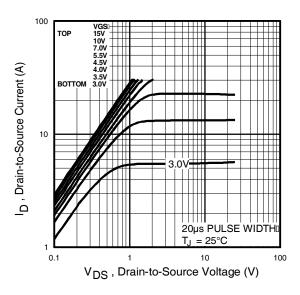
Notes:

- $\begin{tabular}{ll} @ I_{SD} \le 3.8A, \ di/dt \le 220A/\mu s, \ V_{DD} \le V_{(BR)DSS}, \\ T_{J} \le 150 ^{\circ} C \ . \end{tabular}$
- Notes:

 ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
 ② V_{DD} = 25V, starting T_J = 25°C, L = 15mH
 P = 25O I_{AS} = 3.8A. (See Figure 12)

 ④ Pulse width = 3.65--,
 ③ When mounted on FR-4 board using minimum recommended footprint.
 ⑤ When mounted on 1 inch square copper board, for comparison with other SMD devices.





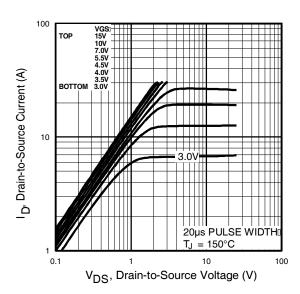
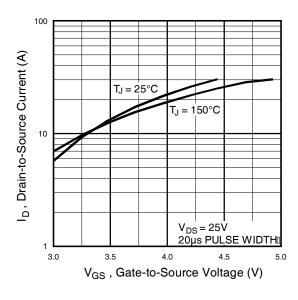


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics



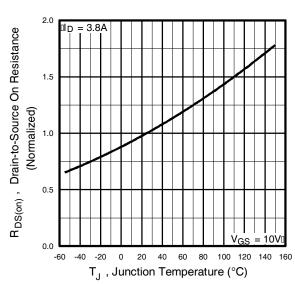
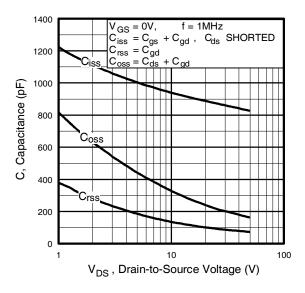


Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance Vs. Temperature





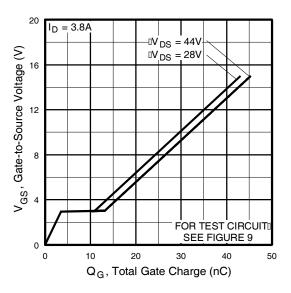
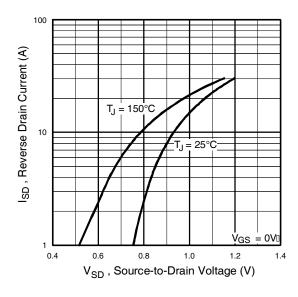


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage



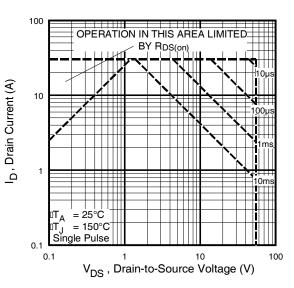


Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area



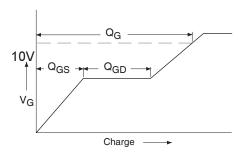


Fig 9a. Basic Gate Charge Waveform

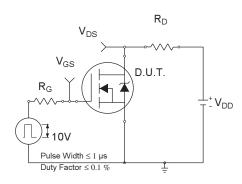


Fig 10a. Switching Time Test Circuit

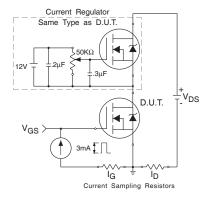


Fig 9b. Gate Charge Test Circuit

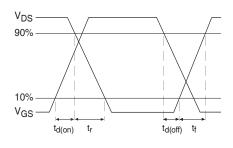


Fig 10b. Switching Time Waveforms

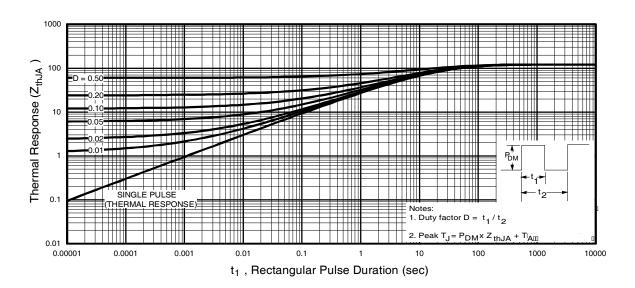


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



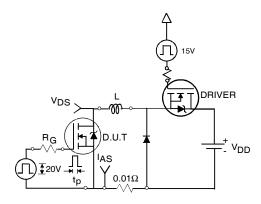
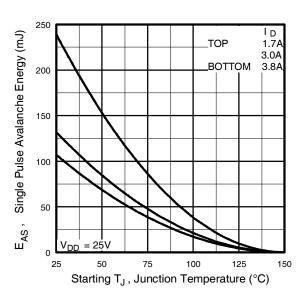


Fig 12a. Unclamped Inductive Test Circuit



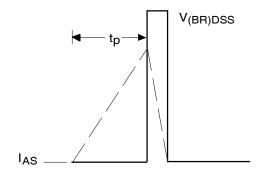
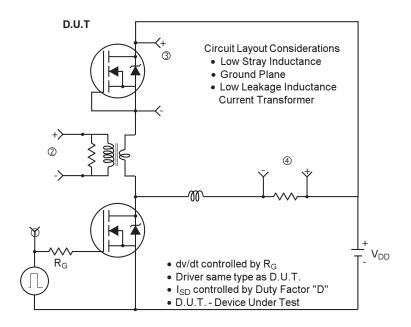


Fig 12b. Unclamped Inductive Waveforms

Fig 12c. Maximum Avalanche Energy Vs. Drain Current



Peak Diode Recovery dv/dt Test Circuit



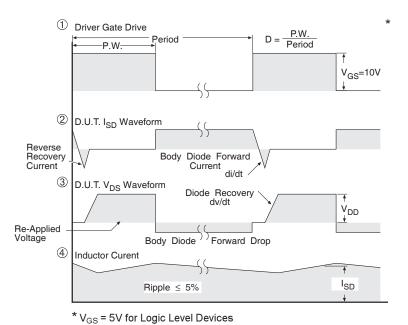
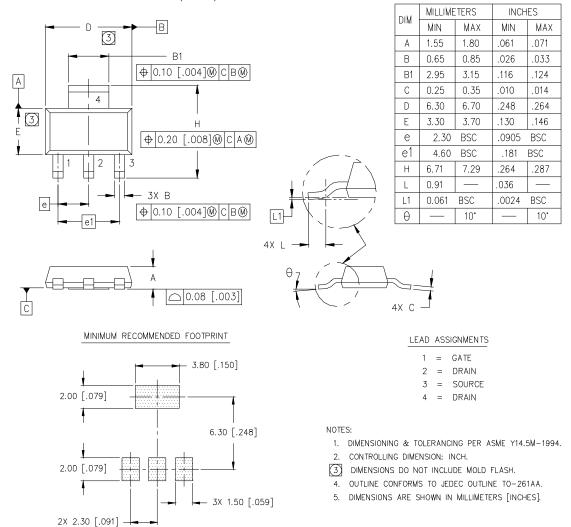


Fig 13. For N-Channel HEXFETS

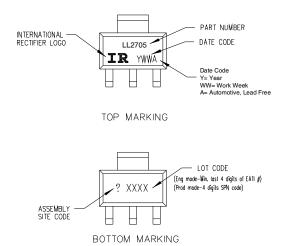


SOT-223 (TO-261AA) Package Outline

Dimensions are shown in milimeters (inches)



SOT-223 (TO-261AA) Part Marking Information

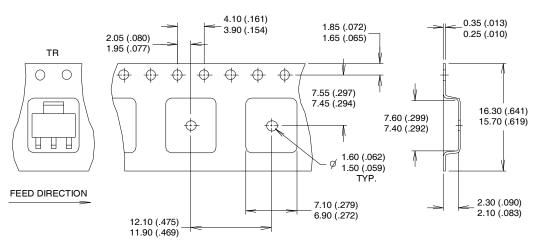


Note: For the most current drawing please refer to IR website at http://www.irf.com/package/



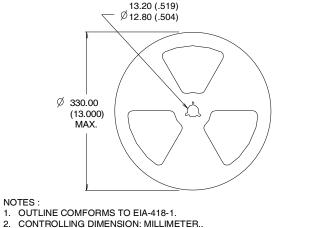
SOT-223 (TO-261AA) Tape & Reel Information

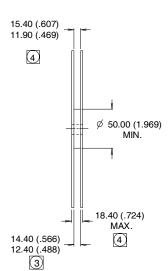
Dimensions are shown in milimeters (inches)



NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER.
- 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.
- 3. EACH Ø330.00 (13.00) REEL CONTAINS 2,500 DEVICES.





- DIMENSION MEASURED @ HUB.
- (3) (4) INCLUDES FLANGE DISTORTION @ OUTER EDGE.

Note: For the most current drawing please refer to IR website at http://www.irf.com/package/



Qualification Information[†]

			Automotive			
quamication Level		(per AEC-Q101) ^{††}				
		qualification.	This part number(s) passed Automotive IR's Industrial and Consumer qualification ed by extension of the higher Automotive			
Moisture Sensitivity Level		SOT-223	MSL1			
Machine Model		Class M2 (+/- 200V) ^{†††}				
		AEC-Q101-002				
FOR	Human Body Model	Class H1B (+/- 750V) ^{†††}				
Charged Device Model		AEC-Q101-001				
		Class C5 (+/- 1125V) ^{†††}				
		AEC-Q101-005				
RoHS Compliant	•		Yes			

- † Qualification standards can be found at International Rectifier's web site: http://www.irf.com/
- †† Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.
- ††† Highest passing voltage.



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WORLD HEADQUARTERS:

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Revision History

Date	Comments
- / / /	Added "Logic Level Gate Drive" bullet in the features section on page 1
3/26/2014	Updated part marking on page 8 Updated data sheet with new IR corporate template